



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

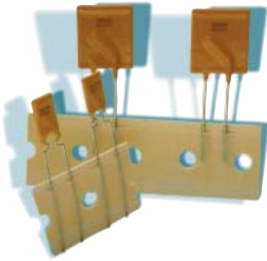
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

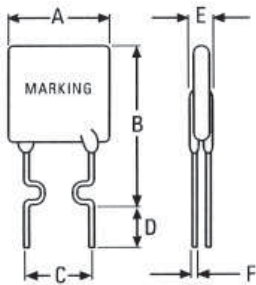
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



RLD30



Dimensions (mm)



Radial Leaded, 30 V

Standard

UL 1434 1st Edition
CSA C22.2 No. 0 CSA TIL No. CA-3A

Approvals

cULus Recognition
TÜV

Features

This 30 V product line can be used in almost anywhere there is a low voltage power supply (<30 V dc) and a load to be protected including

- General electronics
- Computer and Peripherals
- Automotive Electronics

Specifications

Packaging

A* bulk
G tape and reel
F* tape and ammo
* preferred type

Materials

Insulating Material: Yellow Epoxy Polymer, UL 94 V-0

Round Pins: Copper alloy, tin plated

Max. Device Surface Temperature in Tripped State

125 °C

Operating / Storage Temperature

-40 °C to +85 °C (consider derating)

Humidity Ageing

+85 °C, 85 % R.H., 1000 hours, ± 5 % typical resistance change

Soldering Characteristics

Solderability per MIL-STD-202, Method 208E

Thermal Shock

MIL-STD-202F, Method 107G
+125 °C to -40 °C 10 times, ±10 % typical resistance change

Solvent Resistance

MIL-STD-202, Method 215F, no change

Marking

"P", voltage, amperage rating, lot number



Dimensions (mm)

Model	A	B	C	D	E	Physical Characteristics		packaging quantity	
	Max	Max	typ	Min	Max	Lead	Material	bag	ammo
RLD30P090U	7.4	12.2	5.1	7.6	3.0	0.51 dia.	Sn/CuFe	500	2,000
RLD30P110U	7.4	14.2	5.1	7.6	3.0	0.51 dia.	Sn/CuFe	500	2,000
RLD30P135U	8.9	13.5	5.1	7.6	3.0	0.51 dia.	Sn/CuFe	500	2,000
RLD30P160U	8.9	15.2	5.1	7.6	3.0	0.51 dia.	Sn/CuFe	500	2,000
RLD30P185U	10.2	15.7	5.1	7.6	3.0	0.51 dia.	Sn/CuFe	500	2,000
RLD30P250U	11.4	18.3	5.1	7.6	3.0	0.51 dia.	Sn/CuFe	500	2,000
RLD30P300U	11.4	17.3	5.1	7.6	3.0	0.81 dia.	Sn/Cu	500	2,000
RLD30P400U	14.0	20.1	5.1	7.6	3.0	0.81 dia.	Sn/Cu	100	1,000
RLD30P500U	14.0	24.9	10.2	7.6	3.0	0.81 dia.	Sn/Cu	100	1,000
RLD30P600U	16.5	24.9	10.2	7.6	3.0	0.81 dia.	Sn/Cu	100	1,000
RLD30P700U	19.1	26.7	10.2	7.6	3.0	0.81 dia.	Sn/Cu	100	1,000
RLD30P800U	21.6	29.2	10.2	7.6	3.0	0.81 dia.	Sn/Cu	100	1,000
RLD30P900U	24.1	29.7	10.2	7.6	3.0	0.81 dia.	Sn/Cu	100	1,000

Permissible continuous operating current is ≤ 100% at ambient temperature of 20°C (68°F).

Model	I _{hold} (A)	I _{Trip} (A)	V _{max. dc} (V)	I _{max.} (A)	max. time to trip (sec. @ A)	P _{d max.} (W)	Resistance		Approvals	
							R _{min.} (Ω)	R _{I max.} (Ω)	cULus	TÜV
RLD30P090U	0.90	1.80	30	40	5.90 @ 4.50	0.6	0.070	0.220	•	•
RLD30P110U	1.10	2.20	30	40	6.60 @ 5.50	0.7	0.050	0.170	•	•
RLD30P135U	1.35	2.70	30	40	7.30 @ 6.75	0.8	0.040	0.130	•	•
RLD30P160U	1.60	3.20	30	40	8.00 @ 8.00	0.9	0.030	0.110	•	•
RLD30P185U	1.85	3.70	30	40	8.70 @ 9.25	1.0	0.030	0.090	•	•
RLD30P250U	2.50	5.00	30	40	10.30 @ 12.50	1.2	0.020	0.070	•	•
RLD30P300U	3.00	6.00	30	40	10.80 @ 15.00	2.0	0.020	0.080	•	•
RLD30P400U	4.00	8.00	30	40	12.70 @ 20.00	2.5	0.010	0.050	•	•
RLD30P500U	5.00	10.00	30	40	14.50 @ 25.00	3.0	0.010	0.050	•	•
RLD30P600U	6.00	12.00	30	40	16.00 @ 30.00	3.5	0.005	0.040	•	•
RLD30P700U	7.00	14.00	30	40	17.50 @ 35.00	3.8	0.005	0.030	•	•
RLD30P800U	8.00	16.00	30	40	18.80 @ 40.00	4.0	0.005	0.020	•	•
RLD30P900U	9.00	18.00	30	40	20.00 @ 40.00	4.2	0.005	0.020	•	•

NOTE:
 I_{hold} = Hold current: maximum current device will pass without tripping in 20 °C still air.
 I_{Trip} = Trip current: minimum current at which the device will trip in 20 °C still air.
 V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})
 I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})

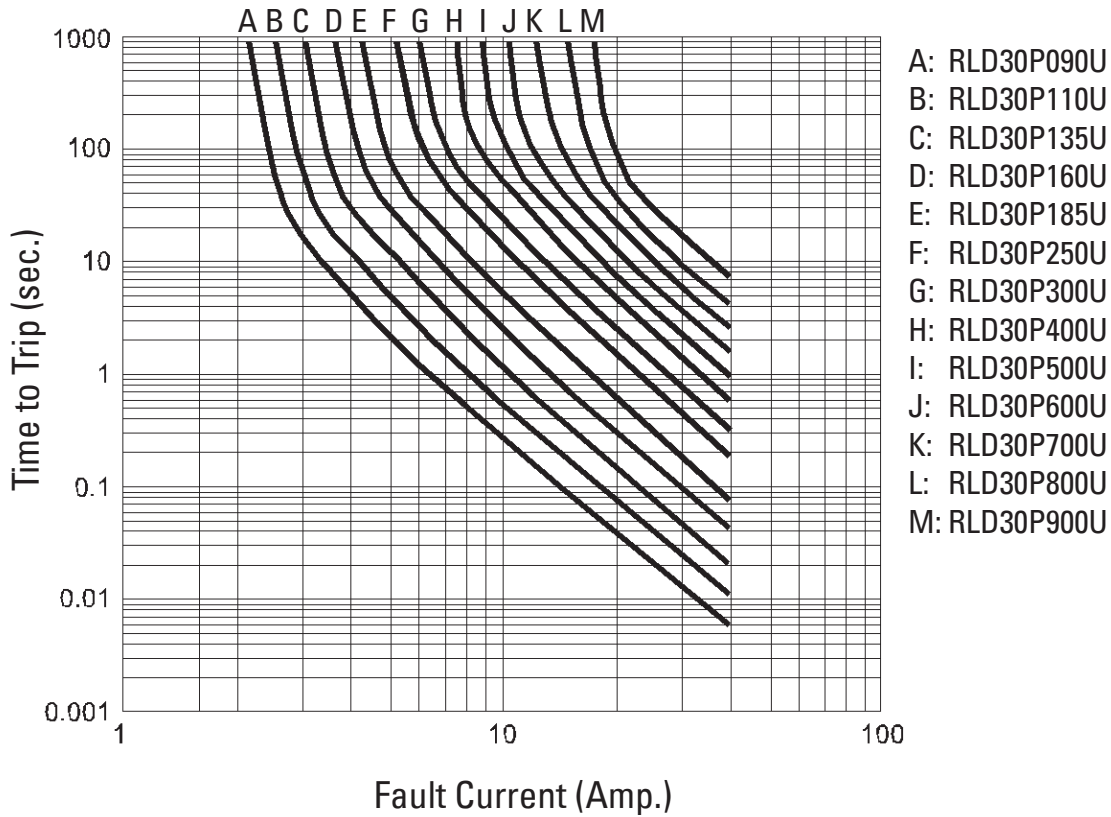
P_d = Power dissipated from device when in the tripped state at 20 °C still air.
 R_{min} = Minimum resistance of device in initial (un-soldered) state.
 R_{I max} = Maximum resistance of device at 20 °C measured one hour after tripping for 20 s.
Caution: Operation beyond the specified rating may result in damage and possible arcing and flame. Specifications are subject to change without notice

Order Information

Qty.	Order-Number	Model	* Packaging
------	--------------	-------	-------------

* optional "F" for lead free devices

RLD30



Thermal Derating Chart

Model	Ambient Operation Temperature - I_{hold} (A)								
	-40 °C	-20 °C	0 °C	23 °C	40 °C	50 °C	60 °C	70 °C	85 °C
RLD30P090U	1.31	1.17	1.04	0.90	0.75	0.69	0.61	0.55	0.47
RLD30P110U	1.60	1.43	1.27	1.10	0.91	0.85	0.75	0.67	0.57
RLD30P135U	1.96	1.76	1.55	1.35	1.12	1.04	0.92	0.82	0.70
RLD30P160U	2.32	2.08	1.84	1.60	1.33	1.23	1.09	0.98	0.83
RLD30P185U	2.68	2.41	2.13	1.85	1.54	1.42	1.26	1.13	0.96
RLD30P250U	3.63	3.25	2.88	2.50	2.08	1.93	1.70	1.53	1.30
RLD30P300U	4.35	3.90	3.45	3.00	2.49	2.31	2.04	1.83	1.56
RLD30P400U	5.80	5.20	4.60	4.00	3.32	3.08	2.72	2.44	2.08
RLD30P500U	7.25	6.50	5.75	5.00	4.15	3.85	3.40	3.05	2.60
RLD30P600U	8.70	7.80	6.90	6.00	4.98	4.62	4.08	3.66	3.12
RLD30P700U	10.15	9.10	8.05	7.00	5.81	5.39	4.76	4.27	3.64
RLD30P800U	11.60	10.40	9.20	8.00	6.64	6.16	5.44	4.88	4.16
RLD30P900U	13.05	11.70	10.35	9.00	7.47	6.93	6.12	5.49	4.68